

MA3XD15

Silicon epitaxial planar type

For high frequency rectification

■ Features

- Low forward voltage: $V_F < 0.45$ V
- Small reverse current: $I_R < 100$ μ A
- Forward current (Average) $I_{F(AV)} = 1$ A rectification is possible

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	20	V
Repetitive peak reverse voltage	V_{RRM}	25	V
Non-repetitive peak forward surge current *2	I_{FSM}	3	A
Forward current (Average) *1	$I_{F(AV)}$	1.0	A
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *1: Mounted on an alumina PC board

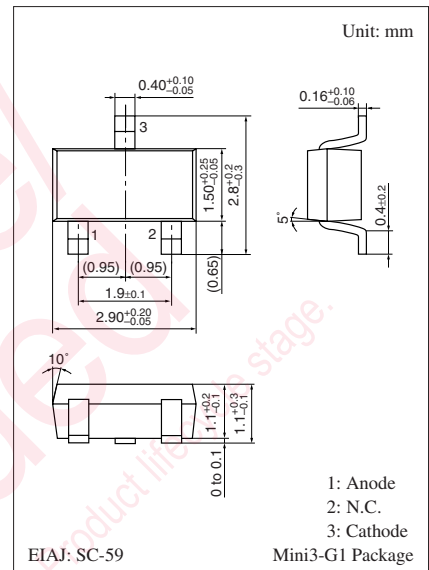
*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 1.0$ A			0.45	V
Reverse current	I_R	$V_R = 20$ V			100	μ A
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		120		pF

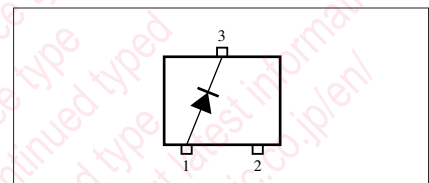
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

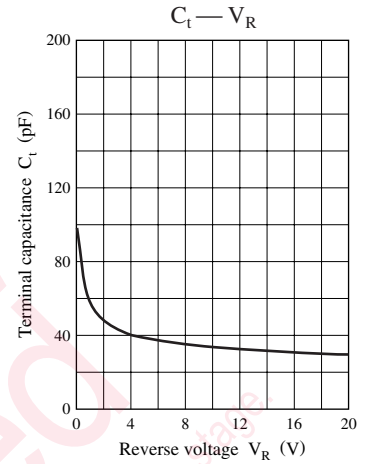
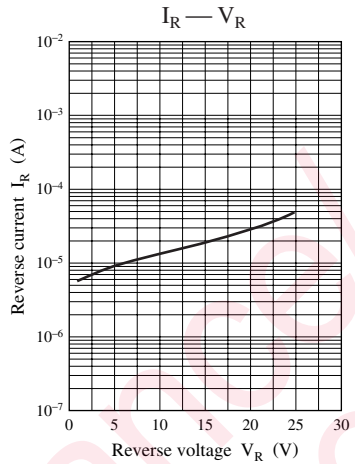
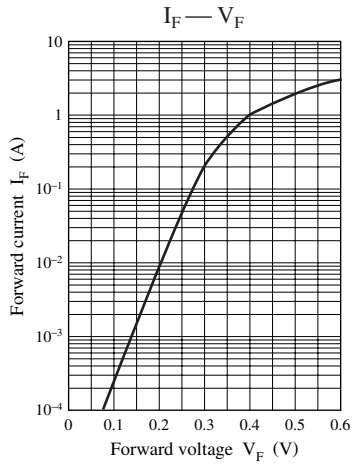
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.



Marking Symbol: M5N

Internal Connection





Maintenance/Discontinued includes following four Product lifecycle types:
 planned maintenance type
 maintenance type
 planned discontinued type
 discontinued type
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